



TYPICAL PROPERTIES & SPECIFICATIONS SHEET

conductive containers, inc.

DESCRIPTION: Inherently Dissipative TPU

APPLICATION: Thermoforming
Long Term Use

CCI PART NUMBER: KleanStat Flex TPU

PROPERTY	VALUE (U.S.)	TEST METHOD
Volume Resistance	10 ⁷ - 10 ⁹	ANSI/ESD STM11.12-2021
Surface Resistance	10 ⁷ -10 ⁹	ANSI/ESD STM11.11-2022
Static Decay Rate (+5000V-50V)	0.01 Sec	FTMS 101-C (12% RH)
Static Decay Rate (-5000V-50V)	0.01 Sec	FTMS 101-C (12% RH)
Static Decay Rate (+1000V-100V)	0.1 Sec	FTMS 101-C (12% RH)
Host Polymer	TPU	-----
Filler	IDP	-----
Color	Transparent	Visual
Specific Gravity	1.16 g/cc	ASTM D-792
Tensile Modulus (@ 100%)	1,200 psi	ASTM D-412
Tensile Modulus (@ 300%)	2,200 psi	ASTM D-412
Tensile Strength (Break)	3,800 psi	ASTM D-412
Tensile Elongation (Break)	450%	ASTM D-412
Shore Hardness	90 A/47 D Shore	ASTM D-2240

CHARACTERISTICS:

- Inherently Static Dissipative
- Melting Temperature: 355 °F
- Ultra-clean: low off-gassing and low ionic contamination
- Rated for 75 °C repeated use
- Available Gauges: .015, .025, .040

APPLICATIONS:

- Medical device packaging
- Electronic component handling
- Component packaging
- Superior cushioning

All values are for pre-formed materials. Electrical values will vary with each individual design.

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